

## An Integrated Registration System for High Technology Multilayer PCBs

## **Terry Haney**

**XACT PCB & Excellon Automation** 







### **Embracing New Technologies to Survive...**









# A definition



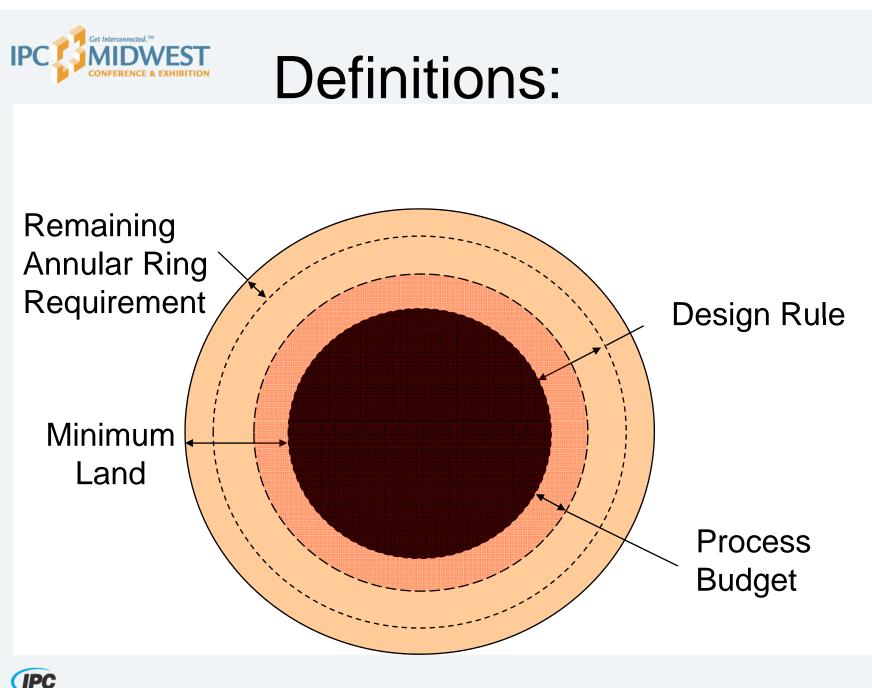


## The Registration Budget The allowance in a PCB design to cope with distortion of the materials, variance of process and manufacturing methods"



Required Annular Ring





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## PCB Registration is like economics:

*"It all works best when you have a BUDGET that you can understand, stay within and balance".* 



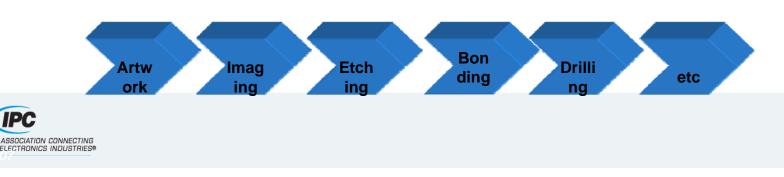






# **Registration Budget**

- Every design has a determinable Registration
  Budget an allowance for the sum of process/material variations
- Every time a compensation is applied at a process step, part of this budget is used up
- Standard "best fit" compensations can use more of the budget than intelligent, process aware compensation systems.







# **Registration Budget**

- If all the registration budget is used up at bonding, then drilling in specification will be impossible
- ... or

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 If all the beer money is gone by Tuesday then Friday night is much less fun!



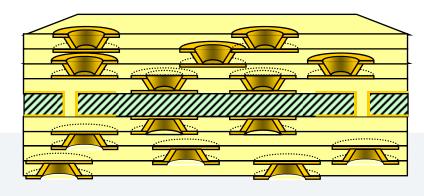


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# **Customer Driven**

- Density demands increasing
- Registration Budget decreasing:
  - Increasing layer count for complex through hole PCBs
  - Tighter design rules: smaller annular ring
    - e.g. CSP, Cell phones etc: increasing level of SBU (up to 4+2+4 and 3+4+3)





## The Registration Challenge: Customer Driven

- Customers require the collation of data from the ENTIRE process to drive process improvement
- Finished PCB dimensional tolerances getting tougher
  - For some designs is not allowed to compensate
  - Prediction of correct scale factor is critical
- Awareness of non linear distortion is increasing rapidly (PCB and OEM)

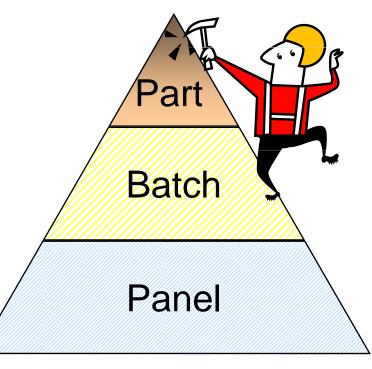




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# The PCB Tooling Challenge



- Currently, PCB shops tool for the part number
- Yet, variation takes place at the batch level
- ..and almost always at the panel level



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# Panel Level Compensation

- Latest generation equipment provides individual panel compensations based upon measurement of targets (e.g. Intelli-Drill®, Laser drill, X-ray/camera aligned drill machines and LDI)
- Registration system can link process data to make INTELLIGENT decisions about subsequent processes.



## Registration system Interface with Optimiser

- Uses standard targets for each layer
  - Linear
    - 4 corner positions
  - NonLinear
    - Multiple peripheral positions
- Registration system reads optimiser's database





### **Collecting Data:**

- Target Acquisition
- Internal Layer Inspection
- Vision Algorithms-X,Y Offset, Rotation, Scaling and Best Fit
- Vision Corrected (Best Fit) Drilling of Circuit Pattern or New Tooling Holes
- Average Best Fit of Tooling for a Batch / Lot of Panels





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It is

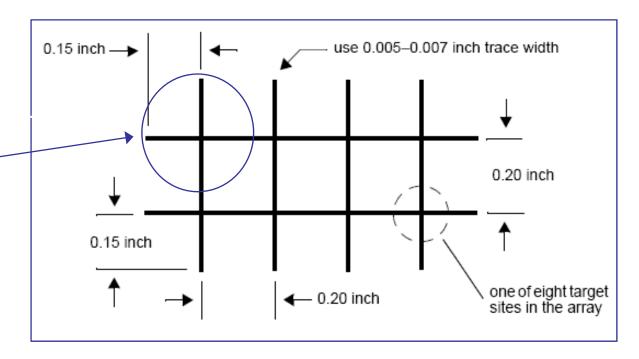
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### **Internal Targets**

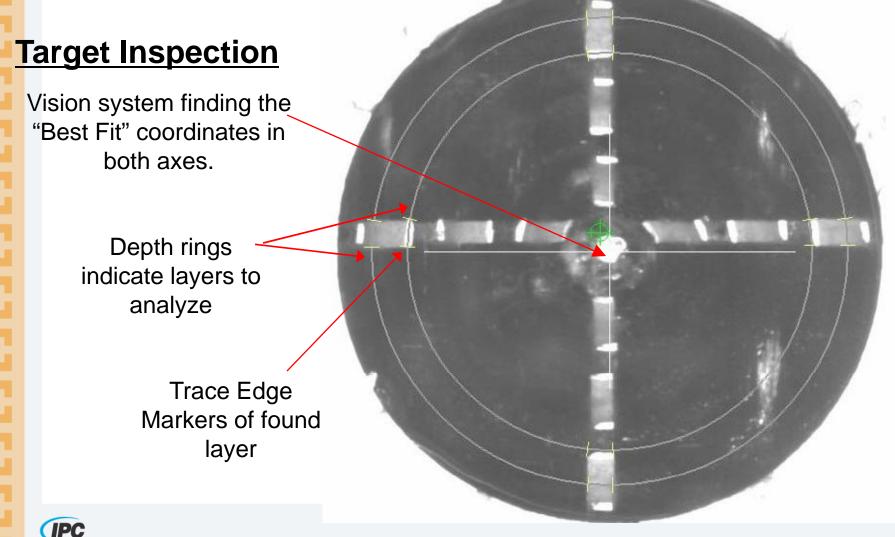


X-Ray would use round images on each layer



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#### **Drill Layer Measurement Data**

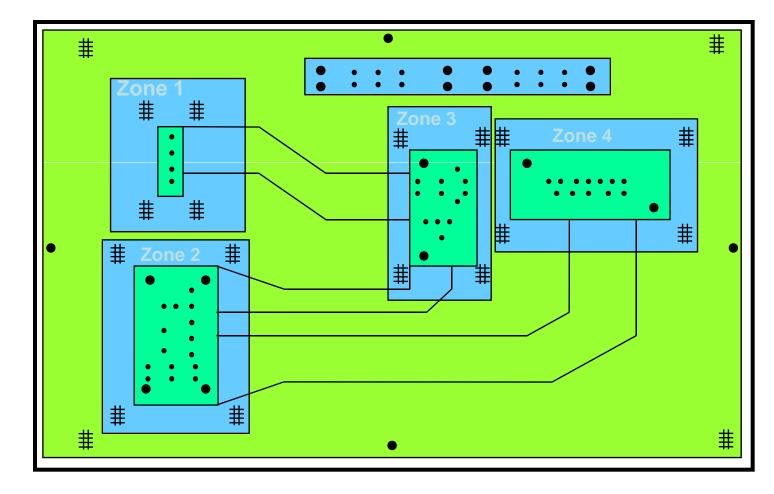
🕎 Drill Layer Measurements: 1

Date/Time	Drill Program	Zone	Group	Layer	Target	X Nominal	Y Nominal	X Offset	Y Offset	TPR
9/21/06 10:23:09	PANEL-01	01	01	02	01	-09.55420	00.76100	00.00720	00.00656	00.00975
9/21/06 10:23:09	PANEL-01	01	01	01	01	-09.55420	00.76100	00.00792	00.00710	00.01064
9/21/06 10:23:09	PANEL-01	01	01	01	02	09.35650	00.76530	-00.00086	00.00595	00.00602
9/21/06 10:23:09	PANEL-01	01	01	01	04	-09.55650	22.27560	00.00606	-00.00557	00.00823
09/21/06 10:23:09	PANEL-01	01	01	02	02	09.35650	00.76530	-00.00185	00.00472	00.00507
9/21/06 10:23:09	PANEL-01	01	01	02	03	09.35430	22.27830	-00.00306	-00.00449	00.00543
9/21/06 10:23:09	PANEL-01	01	01	02	04	-09.55650	22.27560	00.00568	-00.00531	00.00777
9/21/06 10:23:09	PANEL-01	01	01	01	03	09.35430	22.27830	-00.00309	-00.00482	00.00573
9/21/06 11:08:22	PANEL-02	01	01	01	04	-09.55650	22.07560	00.00567	-00.00644	00.00858
9/21/06 11:08:22	PANEL-02	01	01	02	04	-09.55650	22.07560	00.00453	-00.00587	00.00741
9/21/06 11:08:22	PANEL-02	01	01	02	03	09.35430	22.07830	-00.00433	-00.00528	00.00683
9/21/06 11:08:22	PANEL-02	01	01	01	01	-09.55420	00.56100	00.00440	00.00717	00.00841
onstraints									<b>I I</b> 11	•
Data Source	panel			Г	Zone	_ [	Group			
Orill Program	<b>v</b>	Match sul	bstring						Quer	y I
Range	3:09 💉 To 10/20/	06 11:20:4	5 💌	Г	Target		Layer			1

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Vision Corrected Zone Drilling

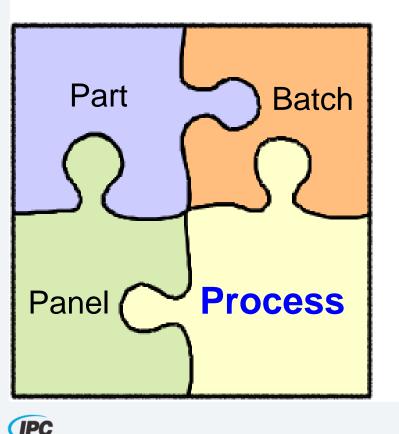
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## Expert Registration System Methodology



- Data drives Intelligent decisions for Tooling and Process
  - Panel,
  - Batch(es),
  - Part number
- Learn about the Process
  and Part number
  requirements by
  understanding the Batch
  and Panel level distortions

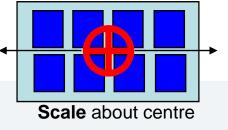
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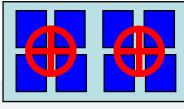
# System's Intelligent Decisions

- Determine the Registration Budget for the product
- Rules-based decisions: Always target nominal at end of process.
  - Apply Linear or Non Linear Scale compensation ?
  - Apply Step only
  - Apply Scale AND Step
  - Do nothing.

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- Establish Product Confidence at each step in the process
- Create modified tooling for downstream processes
- Establish Panel-level / Batch-level traceability



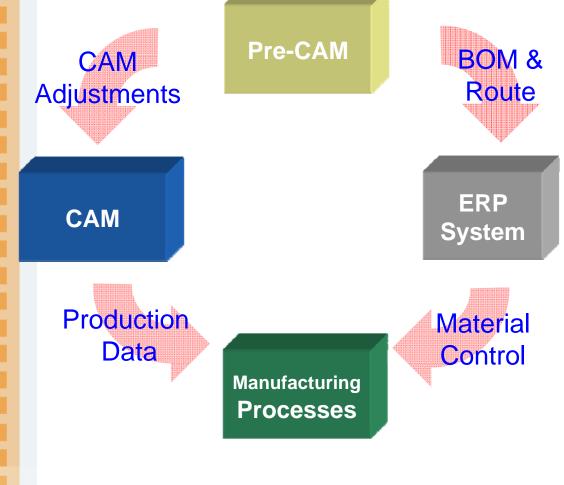


Change circuit **STEP** Means splitting the error



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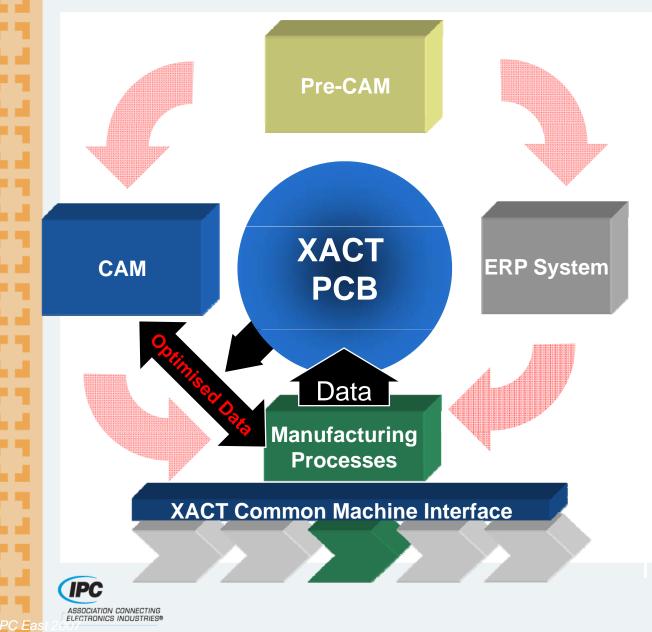
### **Generic Engineering Work Flow**



- Machines and  $\bullet$ CAM are not directly linked
- There is little or no data flow from the process back to CAM & Engineering
- Data is often not centralised



### XACT Linear and Non Linear Control



- Uses a Common Machine Interface to process data from the post bond optimisers
  - Intelli-Drill®
  - X Ray Drill
  - X Ray CMM
  - Etc
- System Returns
  - Intelligent and optimised drill data and scale factors



## **Batch and Panel Analysis**

- System interfaces to production machines via a common graphical interface
- Batch and Panel data can be analysed and compared to previous production
- Closed loop to CAD for batch and (if required) panel compensation



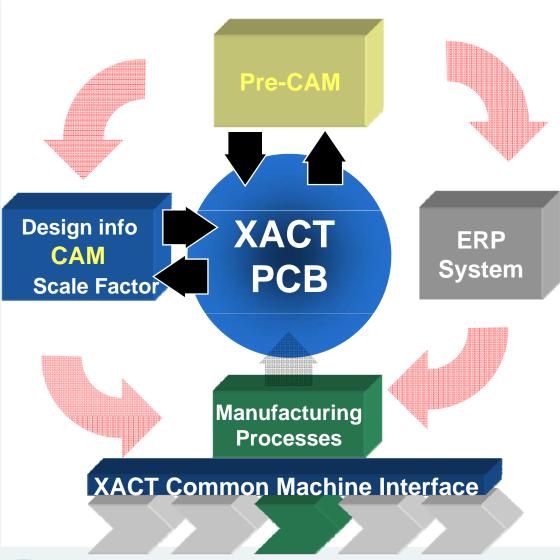


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### Linear and Non Linear Prediction



- Pre-CAM & CAM Provide

   Cu distribution
  - Stackup
- XACT Returns
  - Accurate,
    Predicted
    Layer Scale
    Data
  - Scale Factor Confidence levels and data from previous builds

### IPC MIDWEST Registration system configurations

#### Linear

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Optimises batch-to-batch variability, measure and compensate dynamically. Improves yield immediately

#### Linear+

All the features of Linear combined with advanced prediction capability

#### NonLinear

Linear+ combined with **Non-Linear measurement and compensation** capability

#### NonLinear

Non-linear prediction & compensation capability

Designed for HDI production at the best possible yield



Machine Analysis

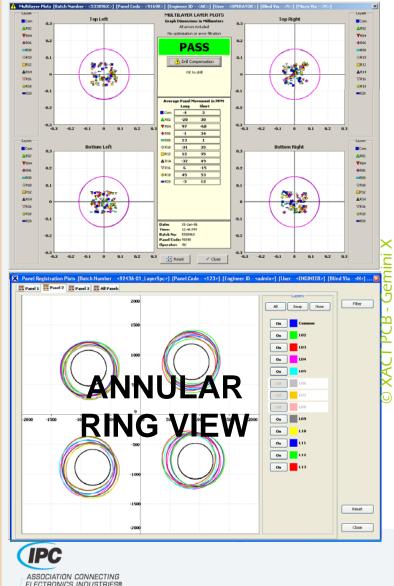
CAM/ERP

Database Drill Optimiser Interfaces Interfaces





### Measurement and Analysis Common Machine Interface



### Linear and Linear+





### Direct link to process machines Improve yields immediately

Feed forward and feed back compensation derived in real time

Reporting for every panel of a batch if required

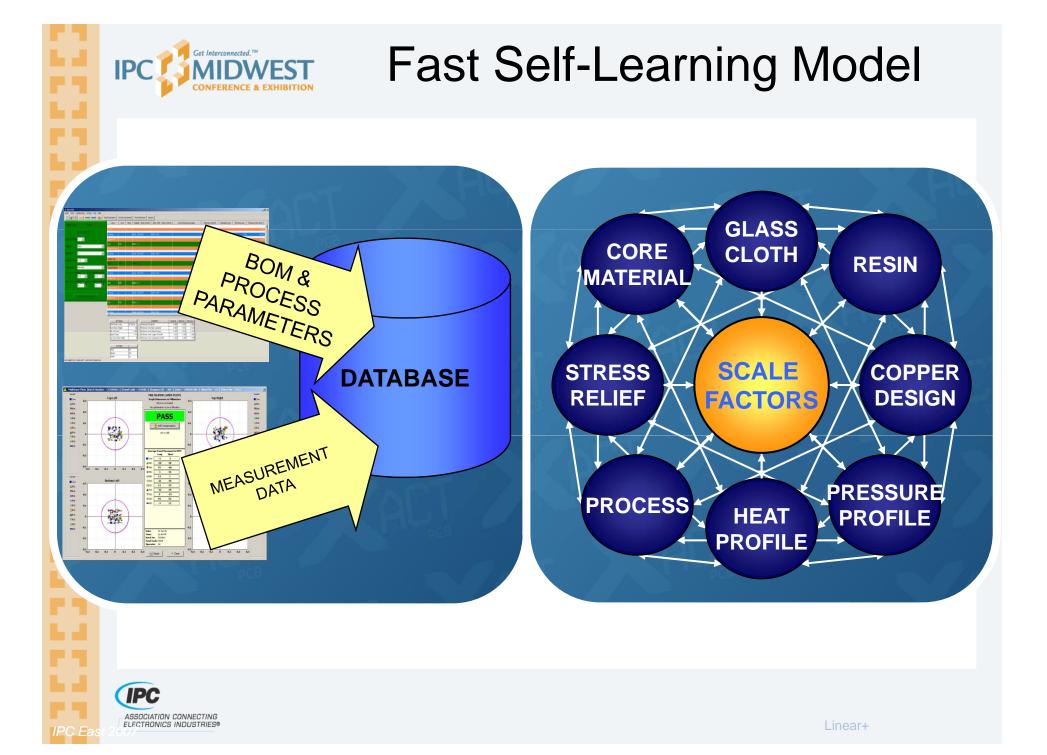


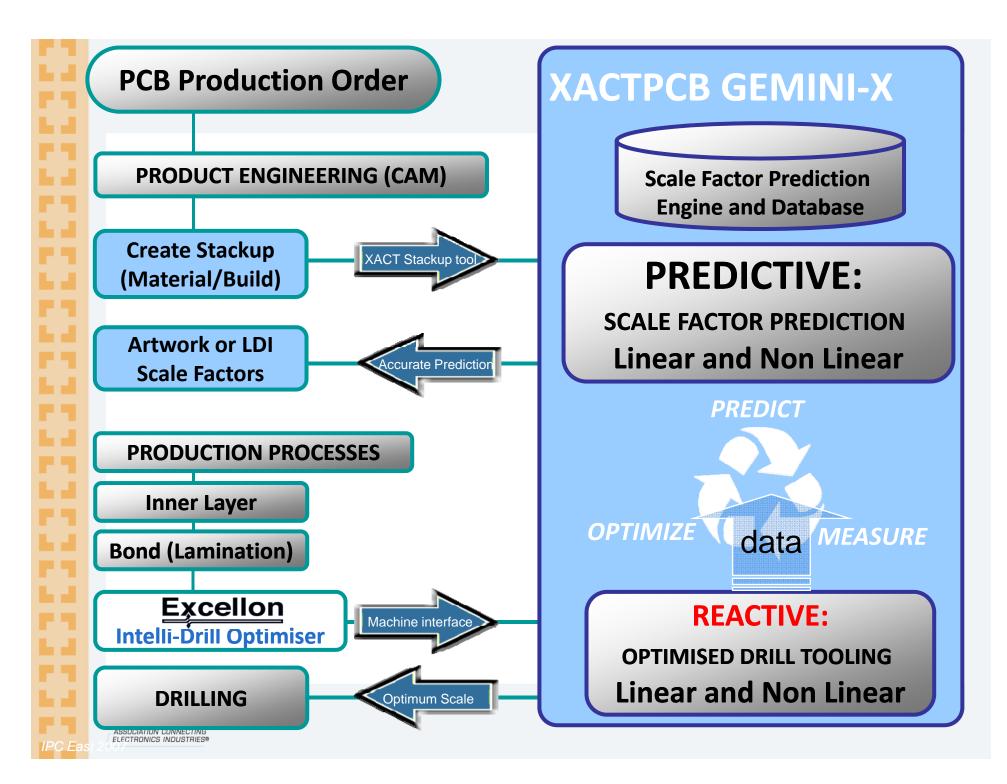


# Registration System Predictive Model

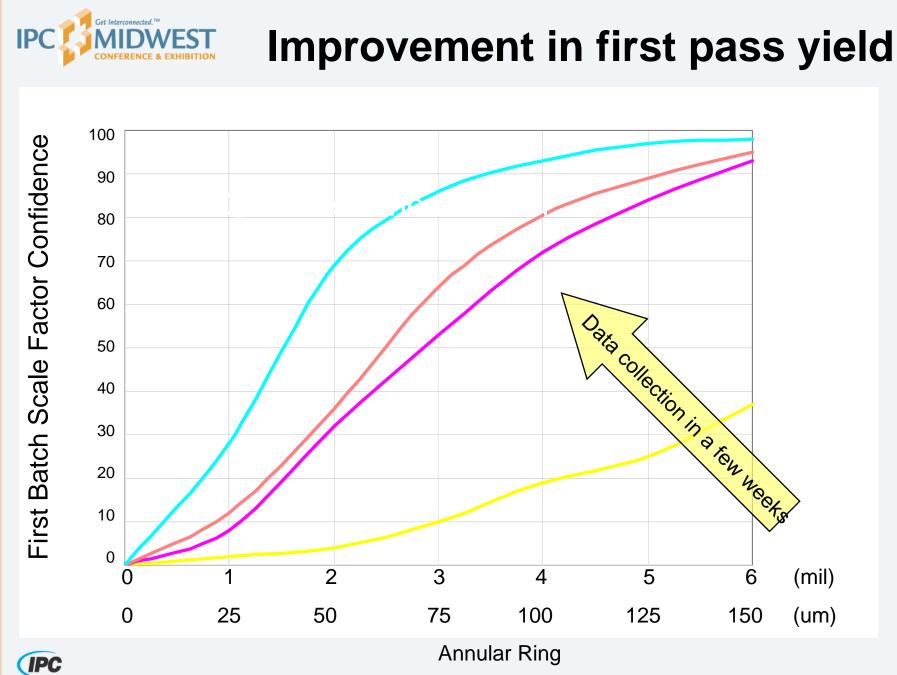
- Self learning model
- Powerful and Fast algorithm
- The model is easy to train
- Implement with CAM
- Unmatched accuracy











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## Conference & exhibition

# Linear+ summary

✓ Interface with existing equipment and data
 ✓ Close the loop between CAD and process

- Predict scale factors with unrivalled accuracy
- No large coupons no loss of expensive real estate
- ✓ Improve yields
- ✓ Reduce leadtime
- Improved throughput
- ✓ Improve profit







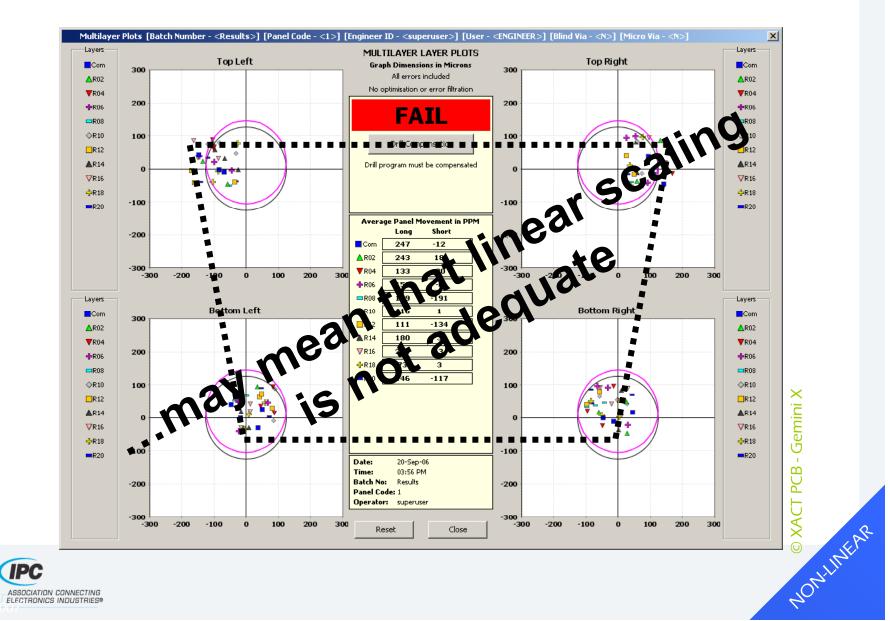
## AND NOW

### "The Rest of the Story"





## Non Linear distortion



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### Non-Linear Measurement (an inner layer core after bonding) Inner layer Core



### Stackup



Each core and the full stackup is characterised by its Non Linear distortion







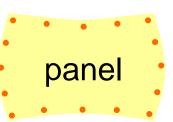
E Configuration				
Report Overlay				
Distortion Model	Panel Selection		Distortion Model (Linear Compensated)	Distortion Model (Non Linear Compensat
	Common      Laver ID        IP      COMMON        IP      E        IP      IN4        IP      IN4        IP      IN14        IP      IN14        IP      IN14        IP      IN14        IP      IN16        IP      IP        IP      IP  <	Colordation P P P P P P P C C C C C C C C C C C C C		
	Average Deviation	210 Microns 76 Microns 75 Percent		
	Average Deviation In Tolesance 1 Non-Linear Compensation Min Design Rule	I⊽ Scale 85 Microns 29 Microns 100 Percent 46 Microns 17 Microns		-300 0 200 100 100 100 100 200
		17 Microns 100 Percent		

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### NonLinear and NonLinear

### **Peripheral measurements**





🕸 X-Act Non-Linear Measurement Analysi	s		
Ele Edit Configuration Help			
Data Report Overlay			
Distortion Model	Analysis Results	Adjusted Distortion Model	$\sim$
	Long Avis Offeet - 46 microns Short Avis Offeet - 15 microns Fortain - 0.0037 degrees Long Avis Distortion - 46 ppm Rhombo Distortion - 46 ppm Long Avis Scale Enc - 271 ppm Oergin Limit - 100 microns Area within Tolerance - 100 percent Area within Tolerance - 52 microns Area within Tolerance - 52 microns Area within Tolerance - 52 microns		ACT PCB - Gemini
			$\mathbf{X}$
-200 0 200	Adjust Model	-200 0 200	
200	Iv Botate ☐ 3D Rotation	200 0 200	U
	Control Layer to Analyse Common Design Rule 120 Apply Rule	100 8 116 200	

### Unique analysis capability

Compensate non linear distortion (Linear and NonLinear reactive capability)

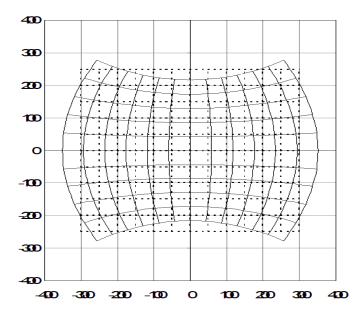
Feedback non linear distortions



# **Non-Linear Prediction**

### Standard process













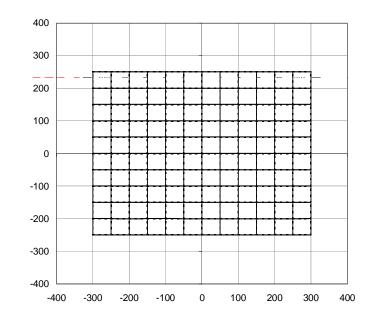


## **Non-Linear Prediction** "Inverse Distortion applied at CAM"

### Non-Linear Compensation At CAM

PC

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# Non Linear+ Summary

- Prediction of non linear distortion:
  - inversely scale artworks or LDI data.
- ✓ Improve HDI capability
- ✓ Design for manufacture verification
- No coupons no loss of expensive real estate
- ✓ Improve yields
- ✓ Reduce leadtime
- ✓ Improve profit







# Summary of System's Solutions

- Instantly improve yields and product quality
- Maximise return from installed capital base
- ROI within weeks
- Reduce lead-time
- Maximise profit
- Link CAM with key shop-floor process controls





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# Conclusions

- Understanding your *registration budget* is critical
- The *registration budget* is going to get tougher and we have to be ready
- The paradigm of tooling only for the part number is changing
- Understanding the process means understanding the batch and panel level variation





- Tools from XACT PCB and Excellon can ensure that you are ready for the next challenges of registration.
- THANK YOU, Excellon®

Precision Drilling • Routing • Micromachining



